



A5N:3000.XXH

VOLTAGE RATINGS

Part Number	V_{RRM} , V_R (V) Max. rep. peak reverse voltage		V_{RSM} , V_R (V) Max. non-rep. peak reverse voltage
	$T_J = 0$ to 125°C	$T_J = -40$ to 0°C	$T_J = 25$ to 125°C
A5N:3000.16H	1600	1600	1700
A5N:3000.18H	1800	1800	1900
A5N:3000.20H	2000	2000	2100
A5N:3000.22H	2200	2200	2300

MAXIMUM ALLOWABLE RATINGS

PARAMETER	VALUE	UNITS	NOTES
T_J Junction Temperature	-40 to 125	$^\circ\text{C}$	-
T_{stg} Storage Temperature	-40 to 150	$^\circ\text{C}$	-
$I_{F(AV)}$ Max. Av. current @ Max. T_C	3000 70	A $^\circ\text{C}$	180° half sine wave
$I_{F(RMS)}$ Nom. RMS current	4700	A	-
I_{FSM} Max. Peak non-rep. surge current	53.3 56 63.3 66.5	KA	50 Hz half cycle sine wave Initial $T_J = 125^\circ\text{C}$, rated V_{RRM} applied after surge. 60 Hz half cycle sine wave 50 Hz half cycle sine wave Initial $T_J = 125^\circ\text{C}$, no voltage applied after surge. 60 Hz half cycle sine wave
I^2t Max. I^2t capability	12020 13065 16992 18470	kA ² s	t = 10ms Initial $T_J = 125^\circ\text{C}$, rated V_{RRM} applied after surge. t = 8.3 ms t = 10ms Initial $T_J = 125^\circ\text{C}$, no voltage applied after surge. t = 8.3 ms
$I^{2t^{1/2}}$ Max. $I^{2t^{1/2}}$ capability	202350	kA ² s ^{1/2}	Initial $T_J = 125^\circ\text{C}$, no voltage applied after surge. I^2t for time $t_x = I^{2t^{1/2}} * t_x^{1/2}$. (0.1 < t_x < 10ms).
di/dt Max. Non-repetitive rate-of-rise current	800	A/ μs	$T_J = 125^\circ\text{C}$, $V_D = V_{DRM}$, $I_{TM} = 1600\text{A}$. Gate pulse: 20V, 20Ω , 10 μs , 0.5 μs rise time, Max. repetitive di/dt is approximately 40% of non-repetitive value.
P_{GM} Max. Peak gate power	16	W	tp < 5 ms
$P_{G(AV)}$ Max. Av. gate power	3.0	W	-
+ I_{GM} Max. Peak gate current	4	A	tp < 5 ms
- V_{GM} Max. Peak negative gate voltage	15	V	-
F Mounting Force	4550	N.m	Non lubricated threads



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CHARACTERISTICS

PARAMETER	MIN.	TYP.	MAX.	UNITS	TEST CONDITIONS
V_{TM} peak on-state voltage	---	1.54	1.62	V	Initial $T_J = 25^\circ\text{C}$, 50-60Hz half sine, $I_{peak} = 9425\text{A}$.
$V_{T(TO)1}$ Low-level threshold	---	---	0.921	V	$T_J = 125^\circ\text{C}$
$V_{T(TO)2}$ High-level threshold	---	---	0.737		Av. power = $V_{T(TO)} * I_{T(AV)} + r_T * [I_{T(RMS)}]^2$
r_{T1} Low-level resistance	---	---	0.079	$\text{m}\Omega$	
r_{T2} High-level resistance	---	---	0.063		Use low values for $I_{TM} < \pi$ rated $I_{T(AV)}$
I_L Latching current	---	270	---	mA	$T_C = 25^\circ\text{C}$, 12V anode. Gate pulse: 10V, 20 Ω , 100 μs .
I_H Holding current	---	100	500	mA	$T_C = 25^\circ\text{C}$, 12V anode. Initial $I_T = 10\text{A}$.
t_d Delay time	---	0.5	1.5	μs	$T_C = 25^\circ\text{C}$, V_D = rated V_{DRM} , 50A resistive load. Gate pulse: 10V, 20 Ω , 10 μs , 1 μs rise time.
t_q Turn-off time	---	---	100	μs	$T_J = 125^\circ\text{C}$, $I_{TM} = 500\text{A}$, $dI/dt = 25\text{A}/\mu\text{s}$, $V_R = 50\text{V}$. $dv/dt = 200\text{V}/\mu\text{s}$ lin. To 80% rated V_{DRM} . Gate: 0V, 100 Ω .
dv/dt Critical rate-of-rise of off-state voltage	500	700	---	V/ μs	$T_J = 125^\circ\text{C}$. Exp. to 100% or lin. Higher dv/dt values available.
	1000	---	---		$T_J = 125^\circ\text{C}$, Exp. To 67% V_{DRM} , gate open.
I_{RM}, I_{DM} Peak reverse and off-state current	---	80	200	mA	$T_J = 125^\circ\text{C}$, Rated V_{RRM} and V_{DRM} , gate open.
I_{GT} DC gate current to trigger	---	---	500	mA	$T_C = -40^\circ\text{C}$
	75	150	250		$T_C = 25^\circ\text{C}$ +12V anode-to-cathode. For recommended
V_{GT} DC gate voltage to trigger	---	---	3.3	V	$T_C = -40^\circ\text{C}$ gate drive see "Gate Characteristics" figure.
	---	1.2	2.5		$T_C = 25^\circ\text{C}$
V_{GD} DC gate voltage not to trigger	---	---	0.3	V	$T_C = 25^\circ\text{C}$, Max. Value which will not trigger with rated V_{DRM} anode-to-cathode.
R_{thJC} Thermal resistance, junction-to-case	---	---	0.011	$^\circ\text{C}/\text{W}$	DC operation.
	---	---	0.012	$^\circ\text{C}/\text{W}$	180° sine wave, double side cooled.
	---	---	0.013	$^\circ\text{C}/\text{W}$	120° rectangular wave, double side cooled.
R_{thCS} Thermal resistance, case-to-sink	---	---	0.006	$^\circ\text{C}/\text{W}$	Mtg. Surface smooth, flat and greased.
wt Weight	---	1590 (56)	---	g(oz.)	---
Case Style	TO-200AE		JEDEC		---

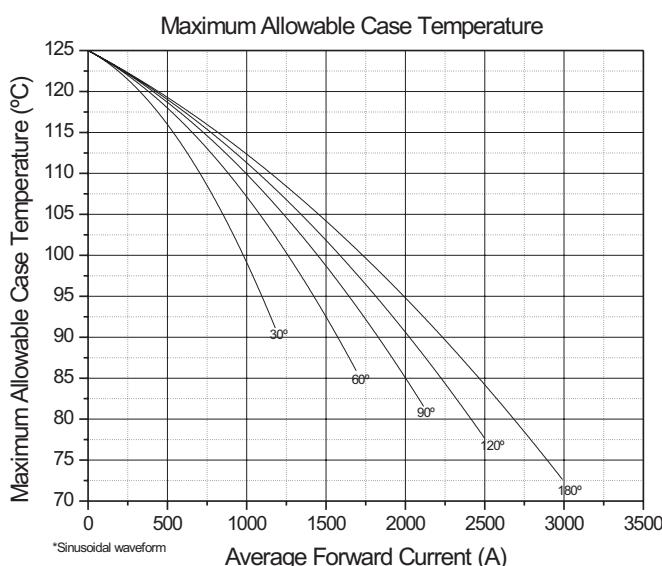


Fig. 1 - Current Ratings Characteristics

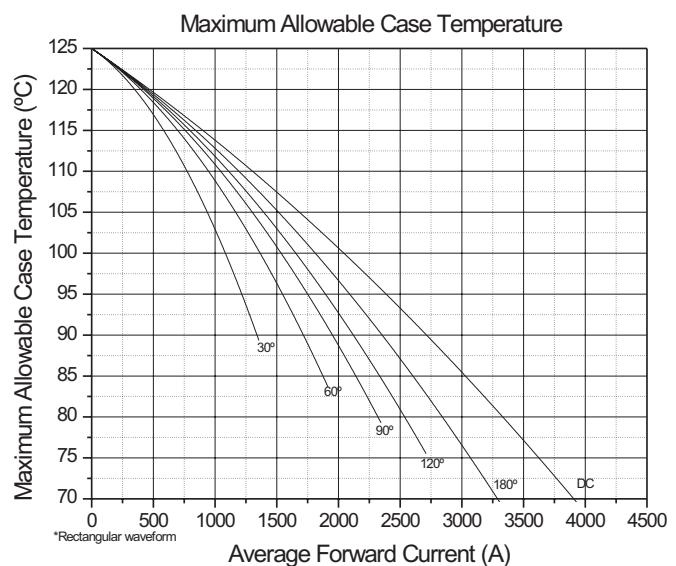


Fig. 2 - Current Ratings Characteristics



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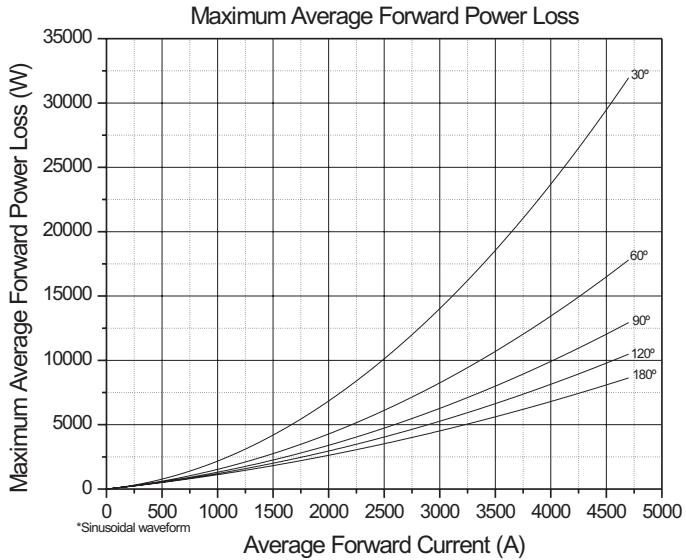


Fig. 3 - Forward Power Loss Characteristics

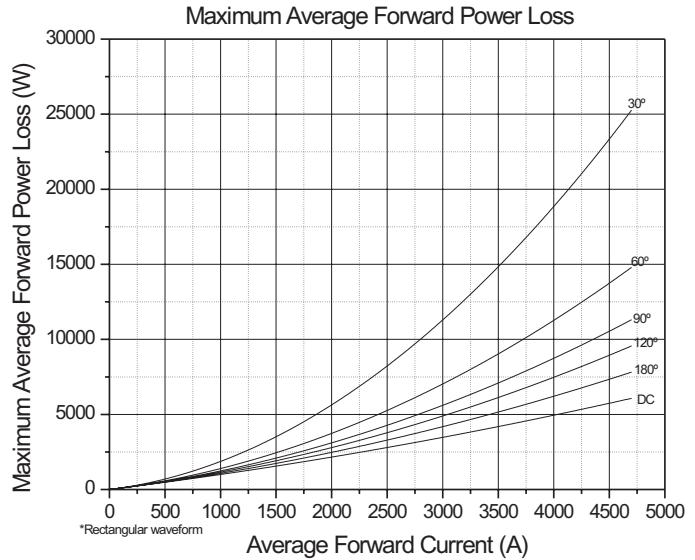


Fig. 4 - Forward Power Loss Characteristics

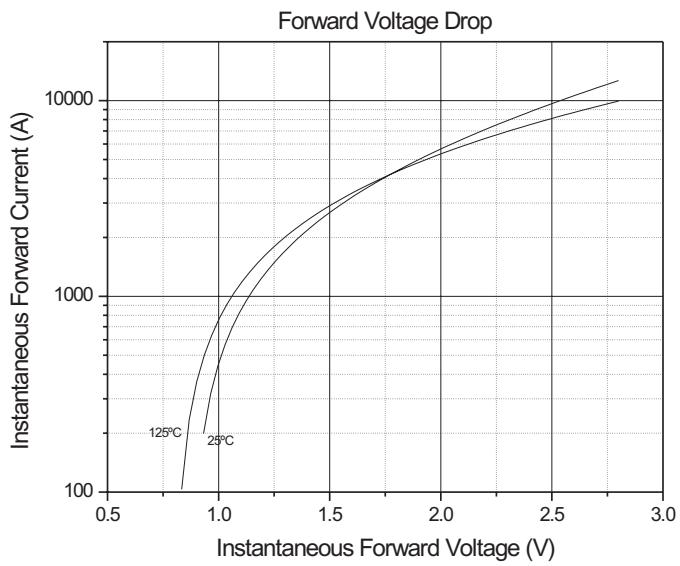


Fig. 5 - Forward Voltage Drop Characteristics

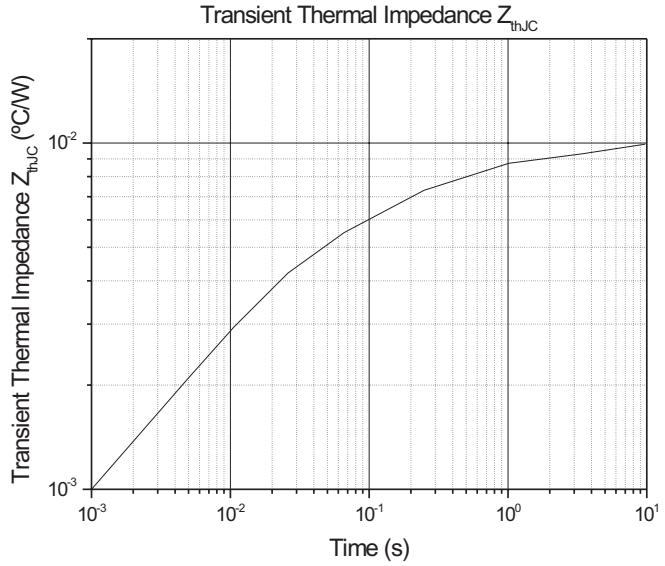


Fig. 6 - Transient Thermal Impedance Characteristics



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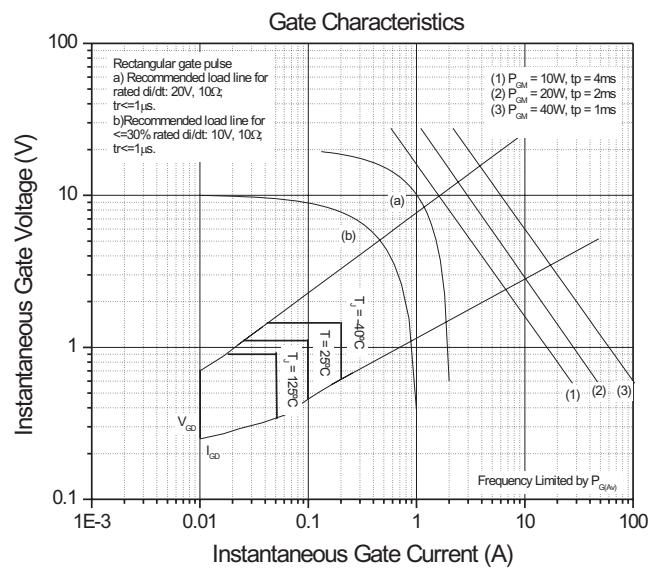


Fig. 7 - Gate Trigger Characteristics

TO-200AE

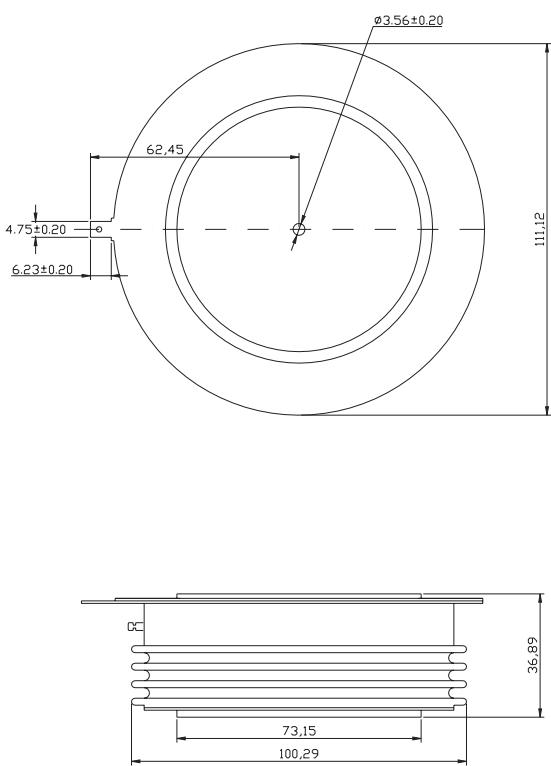


Fig. 8 - Outline Characteristics